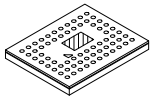


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

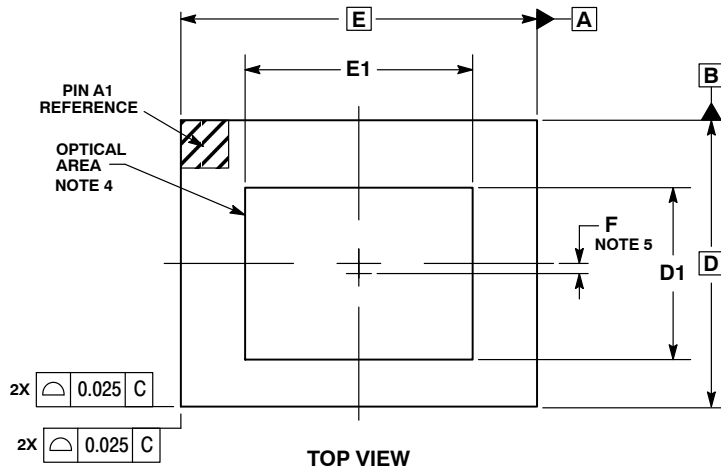
ON Semiconductor®



SCALE 2:1

ODCSP67, 4.93x6.13
CASE 570BW
ISSUE O

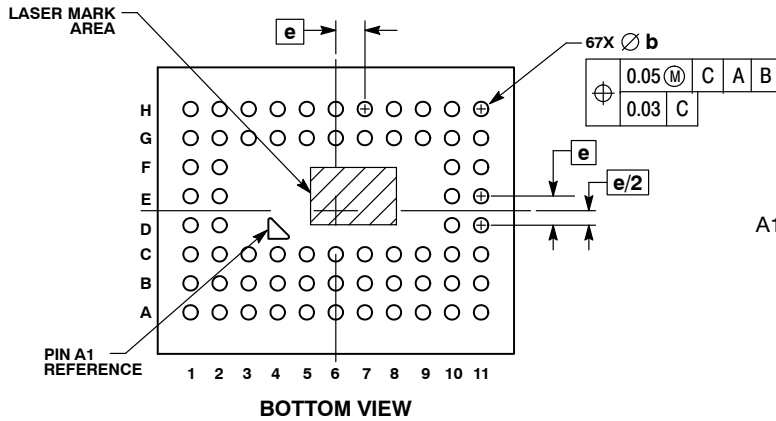
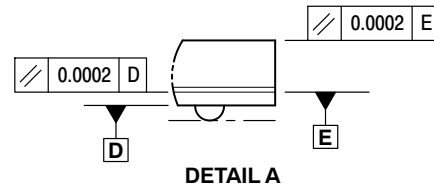
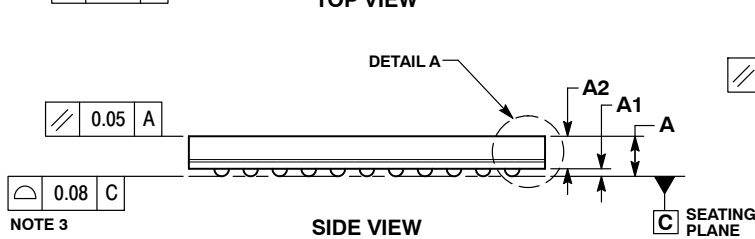
DATE 16 FEB 2016



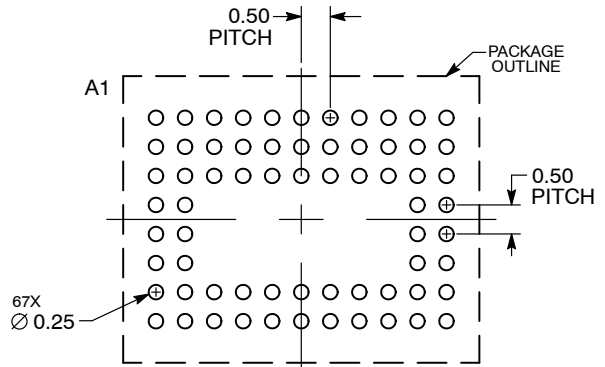
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
4. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES IS 0.1°.
5. DIMENSION F DEFINES THE OPTICAL CENTER.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.75
A1	0.10	0.16
A2	0.56 REF	
b	0.22	0.28
D	4.93 BSC	
D1	2.96 REF	
E	6.13 BSC	
E1	3.92 REF	
e	0.50 BSC	
F	0.175 REF	



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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